



VERSION WITH MARKINGS TO SHOW CHANGES

19.(amended once) A semiconductor chip package, comprising:
a semiconductor chip;
conductive leads electrically connected to and extending over a surface of the
chip;

encapsulating material covering at least a portion of the chip and fully
encapsulating [at least a portion of] the conductive leads; and

electrodes each having a first portion disposed in the encapsulating material and
contacting a conductive lead and a second portion protruding from the encapsulating
material.

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